

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 07304854
PUBLICATION DATE : 21-11-95

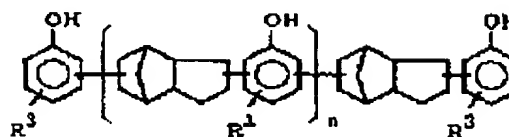
APPLICATION DATE : 11-05-94
APPLICATION NUMBER : 06121811

APPLICANT : TOSHIBA CHEM CORP;

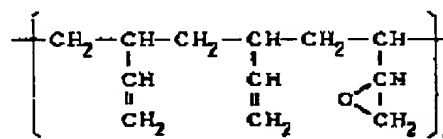
INVENTOR : TSUCHIYA SHINJI;

INT.CL : C08G 59/34 C08G 59/18 C08G 59/62
C08K 3/00 C08L 63/00 H01L 23/29
H01L 23/31

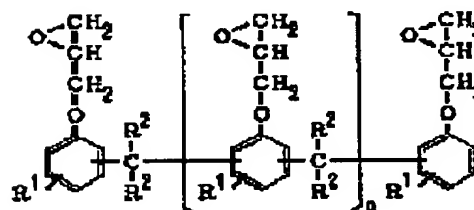
TITLE : PRODUCTION OF EPOXY RESIN
COMPOSITION AND
SEMICONDUCTOR-SEALING DEVICE



I



II



III

ABSTRACT : PURPOSE: To obtain an epoxy resin composition excellent in resistance to reflow cracking after moisture absorption with heat and moisture vapor by dispersing a specific epoxide in a specific phenolic resin and allowing them to react with each other under heating, then heat-kneading the product together with an epoxy resin and an inorganic filler as main starting substances with heat.

CONSTITUTION: In the presence of (A) a hardening accelerator such as an organic phosphine or a tertiary amine, (B) preferably a dicyclopentadiene-phenolic resin of formula I (R^3 is H, methyl; n is 0 or an integer of 1-5) and (C) an epoxy-containing polybutadiene are dispersed, as they are heated to effect their reactions. Then, the resin composition thus obtained is combined with (D) an epoxy resin of formula III (R^1 is H, a halogen, an alkyl; R^2 is H, an alkyl; n is an integer of 1 or more) and (E) an inorganic filler in an amount of 70-90wt.% in total and kneaded with heat to give the objective composition.

COPYRIGHT: (C)1995,JPO